Part Number Customer						
Category	Parameter		Specification	Measurement Method		
OverallWafer	1.0	Silicon Supplier	Topsil Global Wafers			
	2.0	Diameter	100.00 +/- 0.50 mm	WaferVendor		
	3.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor		
	4.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor		
	5.0	Secondary Flat Orientation	none	Wafer Vendor		
	6.0	Overall Thickness	886.00 +/- 7.00 um	Guaranteed by Process		
	7.0	Total Thickness Variation (TTV)	<5.00um	Guaranteed by Process		
	8.0	Bow	<40.00um	Guaranteed by Process		
	9.0	Warp	<40.00um	Guaranteed by Process		
	10.0	Edge Exclusion	5 mm	Guaranteed by Process		
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor		
	12.0	Handle Orientation	<111> off 2.5 - 3.5deg	Wafer Vendor		
	13.0	Handle Thickness	670.00 +/- 5.00 um	Guaranteed by Process		
	14.0	Handle Doping Type	Р	Wafer Vendor		
	15.0	Handle Dopant	Boron	Wafer Vendor		
	16.0	Handle Resistivity	< 0.005	Wafer Vendor		
	17.0	Backside Finish	Lapped and etched with no oxide and lasermark	Wafer Vendor		
DeviceSilicon	18.0	Device Growth Method	FZ	Wafer Vendor		
	19.0	Device Orientation	<111> +/- 1 degree	Wafer Vendor		
	20.0	Nominal Thickness	216.00 +/- 2.00 um	Guaranteed by Process, ADE Single Point, 100%		
	21.0	Distance to device silicon edge from wafer edge	<= 2mm	Guaranteed by Process		
	22.0	Device Doping Type	Р	Guaranteed by Process		
	23.0	Device Dopant	Boron	Guaranteed by Process		
	24.0	Device Resistivity	12000 - 20000 Ohmcm	Wafer Vendor		
	25.0	Voids	none	Guaranteed by Process, SAM inspection		
	26.0	Haze	none	Guaranteed by Process, Bright LIght inspection		
	27.0	Scratches	none	Guaranteed by Process, Bright LIght inspection		

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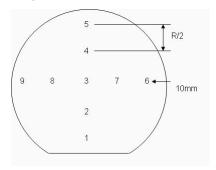
**Product Specification** 

1000.421105

Part Number			Customer		
	Category	Parameter	Specification	Measurement Method	
	Shipping Details	Wafer per box :	Max 25		
		Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging		
		Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
	Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.			

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information